



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE75004-ELD			<b>Issued</b>	28. September 2015			
<b>MA#</b>	MA001400756							
<b>Package</b>	PG-SSOP-14-8			<b>Weight*</b>	83.06 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.099	1.32	1.32	13231	13231
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.689	0.83		8296	
wire	non noble metal	copper	7440-50-8	27.978	33.68	34.56	336849	345664
	non noble metal	copper	7440-50-8	0.446	0.54	0.54	5374	5374
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1217
plastics	plastics	epoxy resin	-	4.648	5.60		55963	
	inorganic material	silicondioxide	60676-86-0	45.774	55.12	60.84	551118	608298
leadfinish	non noble metal	tin	7440-31-5	0.988	1.19	1.19	11899	11899
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9242	9242
glue	plastics	epoxy resin	-	0.131	0.16		1573	
	noble metal	silver	7440-22-4	0.392	0.47	0.63	4719	6292
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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